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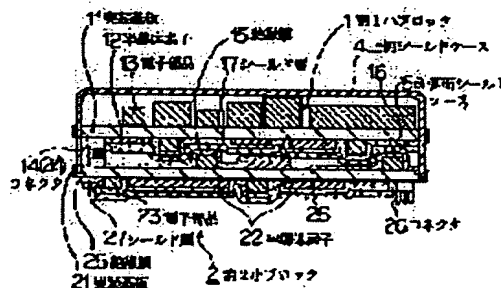
(54) ELECTRONIC CIRCUIT MODULE AND MANUFACTURE THEREOF

(57)Abstract:

PROBLEM TO BE SOLVED: To provide an electronic circuit module composed of electronic circuit small blocks which are laminated close to each other, wherein the blocks are surely insulated from each other, and the circuit module is lessened in thickness and weight at the same time.

SOLUTION: A thin film shielding layer 17 reflecting on the opposed rugged surface of a first small block 1 is interposed between the first small block 1 and a second small block 2 which are electrically connected together with connectors 14 and 24, whereby the small blocks 1 and 2 can be made to confront each other providing the smallest space between them. The shielding layer 17 is formed through a method wherein a thin insulating film

15 is formed on the first small block 1, then conductive paint is sprayed on the insulating film 15 to obtain a coating film, and the layer 17 is formed of the coating film. The shielding layer 17 is connected to the grounding electrode of the first small block 1 through an opening 16. The shielding layer 17 is insulated from the second small block 2 by an insulating film 25 formed on the surface of the second small block 2.



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